

TDK Corporation of America

TDK MLCC Datasheet 1

TDK P/N CGA 2B2 X7R 1H 332 K T

No.	Segment		
(1)	TDK Series Name		
(2)	Dimensions (mm)		
(3)	Thickness T(mm)		
(4)	Voltage Condition for Life Test		
(5)	Temperature Characteristic		
(6)	Rated Voltage (V)		
(7)	Nominal Capacitance		
(8)	Capacitance Tolerance		
(9)	Packaging Information		
-	Dissipation Factor (DF)		
-	Insulation Resistance (IR)		
-	Dielectric Withstanding (DWV)		
-	Storage Temperature Range		
-	Soldering Method		

Detail CGA Series(For Automotive) 1.00 x 0.50 0.50 2 x 50 V -55°C to 125°C, ± 15% 50 V 3,300 pF ±10% Punched (Paper)Taping [180mm Reel] 3% Max 10,000 MOhm Min 125V 5°C to 40°C @ 20~70% RH

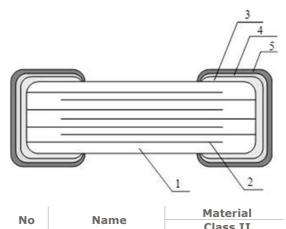
Reflow, Manual

Comments Automotive Grade - Qualification based on CDF-AEC-Q200 See Below for Dimensions Refer to TDK's CGA Specification for Test Method Class II; Conforms to EIA 198. DC 1.0±0.2Vrms; 1kHz ± 10% Conforms to IEC 384-9 EIA 481 format 1.0 ± 0.2 Vrms; 1kHz ± 10% Apply rated voltage for 60 secs at 25°C VDC applied for 1~5s; Charge/Discharge current ≤ 50mA 6 Months Maximum

Soldering technique based on chip shape

Physical Dimensions L G W W

Symbol	Dimensions (mm)
L	1.00 ± 0.05
w	0.50 ± 0.05
Т	0.50 ± 0.05
В	0.15 Min
G	0.35 Min



Material System

No	Name	Material
		Class II
1	Dielectric	BaTiO ₃
2	Electrode	Nickel (Ni)
3		Copper (Cu)
4	Termination	Nickel (Ni)
5		Tin (Sn)

1 This datasheet is to be used for reference purposes only and is subject to change by TDK without notice. It reflects an overview of the product characteristics/performance for the particular part number. For product specification information, please refer to TDK's CGA product specification. Please note that this part is not designed or warranted to meet any specifications of any intermediate or end user different from or in addition to the specifications set forth in TDK's CGA product specification. Note also that this part has not been specially designed or manufactured for, nor is it intended or warranted for use in, or permitted to be resold for, specialized applications such as aviation, medical, and/or governmental/military applications (collectively, "Excluded Applications").









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